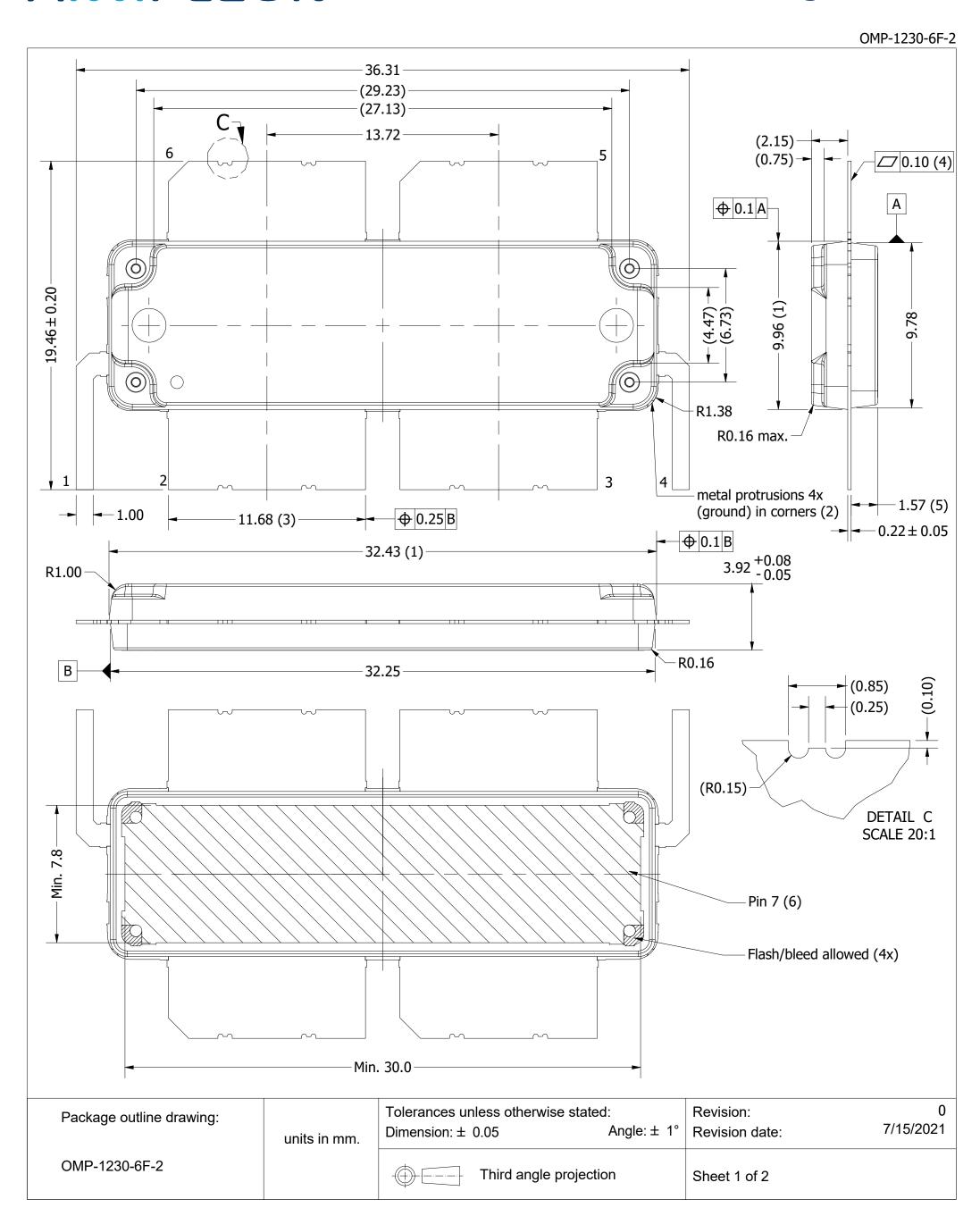
AMPLEON

Package outline





Package outline

OMP-1230-6F-2

| Drawing Notes | |
|---------------|--|
| Items | Description |
| (1) | Dimensions are excluding mold protrusion. All areas located adjacent to the leads have a maximum mold protrusion of 0.2 |
| | mm (per side) and max. 0.62 mm in length. |
| | At all other areas the mold protrusion is maximum 0.15 mm per side. See also detail B. |
| (2) | The metal protrusion (tie bars) in the corner will not stick out of the molding compound protrusions (detail A). |
| (3) | The lead dambar (metal) protrusions are not included. Add 0.14 mm max to the total lead dimension at the dambar location |
| (4) | The lead coplanarity over all leads is 0.1 mm maximum. |
| (5) | Dimension is measured from bottom of lead to bottom of plastic package. |
| | Dimension is measured 0.5 mm from the edge of the package body. |
| (6) | The hatched area indicates the exposed metal heatsink. |
| (7) | The leads and exposed heatsink are plated with matte Tin (Sn). |

